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INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Applicant(s)			
(Use several sheets if necessary)				Fortin, Vincent et al.			
				Filing Date		Group	
				1/23/02		Not yet known	
U.S. Patent Documents							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
Lee	AA	6,355,524 B1	3/12/02	Tuan et al.	438	257	8/15/00
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
Lee	AC	"Handbook of Semiconductor Manufacturing Technology" (2000), edited by Y. Nishi et al., pages 395-413					
	AD	H. Li et al., "Gaseous Impurities in Co Silicidation", Journal of The Electrochemical Society, 148 (6) G344-G354 (2001)					
	AE	S. Wolf, "Silicon Processing for the VLSI Era", vol. 2 (1990), page 246.					
	AF	S.P. Muraka, "Self-aligned silicides or metals for very large scale integrated circuit applications", Vac. Sci. Technol. B 4 (6), Nov/Dec 1986, pages 1325-1331					
	AG	G.L. Miles et al., "TiSi ₂ phase transformation characteristics on narrow devices", Thin Solid Films 290-291 (1996), pages 469-472					
	AH	J.P. Gambino et al., "Silicides and ohmic contacts", Materials Chemistry and Physics 52 (1998), pages 99-146					
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	AK	"Applied Materials Launches Advanced Cobalt Solution for Nano-Chip Manufacturing", Santa Clara, Calif. (Business Wire), http://www.businesswire.com/cgi-bin/cnnisplay.cgi?... Dec. 4, 2001 (1 page)					
	AL	J.B. Lasky et al., "Comparison of Transformation to Low-Resistivity Phase and Agglomeration of TiSi ₂ and CoSi ₂ ", IEEE Transactions on Electron Devices, Vol 38, No. 2, February 1991, pages 262-269					
Lee	AM	"Liner/Barrier & Tungsten ", http://www.appliedmaterials.com/products/ism_liner.html , 1/16/02 (4 pages)					
Examiner	Date Considered		8/6/02				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.							

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